

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|---|----------------------------------|------------------|
| 2 | 53446 | substrate near5 bond\$3 | USPAT; US-PGPUB | 2003/05/11 17:17 |
| 3 | 38607 | (substrate near5 bond\$3) and (remov\$3 detach\$3) | USPAT; US-PGPUB | 2003/05/11 17:13 |
| 4 | 2959 | ((substrate near5 bond\$3) and (remov\$3 detach\$3)) and (metal near5 wir\$3) | USPAT; US-PGPUB | 2003/05/11 17:17 |
| 5 | 2279 | ((substrate near5 bond\$3) and (remov\$3 detach\$3)) and (metal near5 wir\$3)) and (insulat\$3 dielectric) | USPAT; US-PGPUB | 2003/05/11 17:17 |
| 6 | 115 | (remov\$3 separat\$3 detach\$3) near10 (metal near5 wire) near10 (base substrate) | USPAT; US-PGPUB | 2003/05/11 14:54 |
| 7 | 168 | (remov\$3 separat\$3 detach\$3) near10 (metal near5 wire) near10 (base substrate) | EPO; JPO; DERWENT; IBM_TDB | 2003/05/11 14:55 |
| 8 | 33518 | substrate near5 bond\$3 | EPO; JPO; DERWENT; IBM_TDB | 2003/05/11 17:13 |
| 9 | 3974 | (substrate near5 bond\$3) and (remov\$3 detach\$3) | EPO; JPO; DERWENT; IBM_TDB | 2003/05/11 17:13 |
| 10 | 924 | ((substrate near5 bond\$3) and (remov\$3 detach\$3)) and (insulat\$3 dielectric) | EPO; JPO; DERWENT; IBM_TDB | 2003/05/11 17:13 |
| 11 | 24 | ((substrate near5 bond\$3) and (remov\$3 detach\$3)) and (insulat\$3 dielectric)) and (metal near5 wir\$3) | EPO; JPO; DERWENT; IBM_TDB | 2003/05/11 17:14 |
| 12 | 22356 | connection near5 substrate | USPAT; US-PGPUB | 2003/05/11 17:24 |
| 13 | 2372 | (connection near5 substrate) and (metal near5 wir\$3) | USPAT; US-PGPUB | 2003/05/11 17:24 |
| 14 | 2087 | ((connection near5 substrate) and (metal near5 wir\$3)) and (insulat\$3 dielectric) | USPAT; US-PGPUB | 2003/05/11 17:18 |
| 15 | 1186 | ((connection near5 substrate) and (metal near5 wir\$3)) and (insulat\$3 dielectric)) and glass | USPAT; US-PGPUB | 2003/05/11 17:24 |
| 16 | 13250 | connection near5 substrate | EPO; JPO; DERWENT; IBM_TDB | 2003/05/11 17:24 |
| 17 | 276 | (connection near5 substrate) and (metal near5 wir\$3) | EPO; JPO; DERWENT; IBM_TDB | 2003/05/11 17:24 |
| 18 | 19 | ((connection near5 substrate) and (metal near5 wir\$3)) and glass | EPO; JPO; DERWENT; IBM_TDB | 2003/05/11 17:24 |